C2000 LED BoosterPack

User's Guide



Literature Number: SPRUHH9 July 2012



Contents

1	C2000	LED BoosterPack Overview	. 4
	1.1	Overview	. 4
2	Getting	Familiar With the Kit	. 5
	2.1	Kit Contents	. 5
	2.2	Kit Specifications	. 5
3	Hardwa	re Overview	. 5
	3.1	Subsystems	. 6
	3.2	Powering the Board	. 7
	3.3	Boot Modes	. 8
4	Getting	Started	. 8
	4.1	PC GUI Demo	. 8
	4.2	Capacitive Touch Demo	10
5	Hardwa	re Resource Mapping	12
	5.1	Resource Allocation	12
	5.2	Jumpers, Connectors, and Switches	13



List of Figures

1	LED BoosterPack (BOOSTXL-C2KLED)	4
2	Lighting System Topology	5
3	LED BoosterPack Circuit Diagram	6
4	LED BoosterPack Subsytem Locations	7
5	LED BoosterPack GUI	9
6	GUI Setup Connections Window	10
7	LED BoosterPack With C2000 LaunchPad and MSP430 Capacitive Touch BoosterPack	11
8	LED BoosterPack Circuit Diagram	13
9	LED BoosterPack Jumper, Connector, and Switch Locations	14

List of Tables

1	Boot Options	8
2	PWM and ADC Resource Allocation	12
3	Description of Jumpers, Connectors, and Switches	13



User's Guide SPRUHH9–July 2012

C2000 LED BoosterPack

1 C2000[™] LED BoosterPack Overview

1.1 Overview

The LED BoosterPack is an add-on board designed to fit the C2000 LaunchPad and the other 40-pin based LaunchPads. This BoosterPack provides users with a way to accurately control a series of LED strings while efficiently controlling the power stages needed to make the LEDs work. This user's guide discusses the LED BoosterPack kit contents, the board hardware details, and also explains the functions and locations of jumpers and connectors present on the board. Step-by-step instructions for two demo examples are also included.



Figure 1. LED BoosterPack (BOOSTXL-C2KLED)

C2000, LaunchPad, controlSUITE, Code Composer Studio are trademarks of Texas Instruments. Microsoft is a registered trademark of Microsoft Corporation in the United States and/or other countries. All other trademarks are the property of their respective owners.



2 Getting Familiar With the Kit

2.1 Kit Contents

The kit consists of:

- LED BoosterPack
- AC/DC Power Adapter (12 V 1A)
- Quick Start Guide

2.2 Kit Specifications

The LED BoosterPack has the following specifications:

- Power Input:
 - 6 V minimum @ 1.2A
 - 20 V maximum @ 360 mA
- Boost Stages (each):
 - Input
 - 6 V minimum @ 400 mA
 - 20 V maximum @ 120 mA
 - Output
 - 24 V nominal @ 100 mA

3 Hardware Overview

Figure 2 illustrates a LED lighting system running from DC power.



Figure 2. Lighting System Topology

There are multiple ways of controlling LEDs. This board uses the C2000 devices to control a separate DC supply for each of the LED strings. Brightness control is accomplished using the C2000 devices by independently varying the output power of each DC/DC stage. This allows the user to control the average current passing through each LED string. Since average current is roughly proportional to lumen output, each LED string's brightness is controlled. Figure 3 shows the circuit diagram for the LED BoosterPack.





Figure 3. LED BoosterPack Circuit Diagram

3.1 Subsystems

The LED BoosterPack board is divided into functional groups referred to as subsystems. The following is a list of the subsystems present on the board and brief descriptions of each:

- Power Supplies Power is supplied to the board via a 12 V AC/DC wall adapter. This power is stepped down using the Buck regulator to generate 5 V. The 5 V is used to power a 3.3 V LDO that supplies power to the 3.3 V device present on the BoosterPack. Both the 3.3 V and 5 V power domains can be selectively jumpered (via J2 and J8, respectively) to supply power to the LaunchPadXL headers.
- Boost Converters Boost converters are used to step up the 12 V input voltage to a voltage high enough to forward bias the LEDs. The boost converters are driven by the EPWM peripheral present on the F28027 device on the C2000 LaunchPad[™].
- Current Feedback Shunt resistors at the base of each LED string are used to convert the LED current into a voltage that can be measured. The voltage from the sense resistors is passed to a set of op-amps to amplify and filter the current feedback signal. They also serve the purpose of driving the analog-to-digital converter (ADC) inputs.
- MSP430 Capacitive Touch The LED BoosterPack includes an MSP430 device and headers such that a Capacitive Touch BoosterPack can be plugged into the LED BoosterPack and used to control the LEDs. Switch S1 can be used to connect or disconnect the MSP430's serial peripheral to the F28027 device's serial peripheral present on the C2000 LaunchPad. If the user wishes to use the capacitive touch demo, ensure S1 is in the up position while S4 on the LaunchPad is in the down position.
 - Advanced users can reprogram the MSP430 present on the LED BoosterPack by using J5.



Figure 4 illustrates the position of these subsystems on the board. The use of a subsystem approach, for different power stages, enables easy debug and testing of one stage at a time.



Figure 4. LED BoosterPack Subsytem Locations

3.2 Powering the Board

The LED BoosterPack has three separate power domains and two major modes of operation: two power domains are the primary power rails that feeds the three DC/DC power stages and the auxiliary power supply rails that power all of the support chips, and is used to power the LaunchPad. The question of which mode of operation should be used depends on whether the board is being used for evaluation or for experimentation.

- Non-Isolated Used to quickly show how the boards function with the supplied firmware. Power for the LaunchPad is supplied via the USB. Power for the LED BoosterPack is supplied via the included 12 V AC/DC adapter. With this configuration, your PC's USB port is connected to the same ground as both the LaunchPad and LED BoosterPack.
 - Jumpers JP1, JP2, and JP3 on the LaunchPad should have jumpers placed on each post.
 - Jumpers J2 and J8 on the LED BoosterPack should NOT have jumpers placed on each post.
 - Connect the USB to the LaunchPad.
 - Connect the included power adapter to the LED BoosterPacks' J1.



- Isolated/Standalone Used to protect the host PC while debugging the application, which may present dangerous voltages to a PC or when the user wants to run a standalone application with a single supply. Power for the entire system (both LaunchPad and LED BoosterPack) is supplied from the 12 V AC/DC wall adapter. The USB can be optionally connected if the user wants to debug the application; in this case, power for the emulator is supplied via USB. This mode provides the user with 2500 Vrms of isolation to protect the computer in the event that dangerous transient voltages are present on the board.
 - Jumpers JP1, JP2, and JP3 on the LaunchPad should NOT have jumpers placed on each post.
 - Jumpers J2 and J8 on the LED BoosterPack should have jumpers placed on each post.
 - Connect the USB (optional, only used for debugging) to the LaunchPad.
 - Connect the included power adapter to the LED BoosterPacks' J1.

3.3 Boot Modes

Table 1 describes the switch settings that are needed for emulation boots as well as booting from FLASH or SCI for the board.

	Emulation Boot	Boot From FLASH	Boot From SCI
F2802x	SW1 on LaunchPad	SW1 on LaunchPad	SW1 on LaunchPad
	Position 1 = up	Position 1 = up	Position 1 = up
	Position 2 = up	Position 2 = up	Position 2 = down
	Position 3 = up	Position 3 = down	Position 3 = down

Table 1. Boot Options

4 Getting Started

4.1 PC GUI Demo

The LED BoosterPack experimenter's kit comes with a GUI that provides a convenient way to evaluate the functionality of this kit and the F28027 device without having to learn and configure the underlying project software. The interactive interface using sliders, buttons, and textboxes allows LED lighting with the C2000 device to be demonstrated quickly and easily.

4.1.1 Hardware Setup for PC GUI Demo

Perform or verify the following steps to prepare the LED BoosterPack for use with the included GUI:

- 1. Verify the following jumper and switch settings on the LED BoosterPack.
 - (a) A jumper is not placed on J2.
 - (b) A jumper is not placed on J8.
 - (c) The switch S1 is in the down position.
- 2. Verify the following jumper and switch settings on the C2000 LaunchPad:
 - (a) A jumper is placed on JP1.
 - (b) A jumper is placed on JP2.
 - (c) A jumper is placed on JP3.
 - (d) Switches in S1 are all in the up position.
 - (e) The switch S4 is in the up position.
- 3. Insert a C2000 LaunchPad into the header marked J3, J9 and J4, J10.
- 4. Connect the LED BoosterPack to the included power adapter and plug in the adapter to the mains power.
- 5. Connect the LaunchPad to the PC using the USB cable included with the C2000 LaunchPad.

4.1.2 Software Setup for PC GUI Demo

The GUI for evaluating this kit is named *LED_BOOST_PC_GUI.exe* and can be found in the C2000 LaunchPad controlSUITE[™] package. This GUI is all the software necessary to do a quick evaluation of this kit. To explore deeper, the underlying reference software can be found within controlSUITE.

NOTE: The GUI requires Microsoft[®] .NET framework 3.0 to run. Please ensure that this software is installed prior to running this program.

If this demo is being used on a computer that uses a decimal comma, the regional settings of the computer may need to be changed to English for this demo to run correctly.

Follow these instructions to run the GUI included with the LED BoosterPack:

- 1. Start Code Composer Studio[™] version 5.
- 2. In TI Resource Explorer, look for an entry called controlSUITE and expand the Development Tools section.
- Expand the entry for BOOSTXL-C2KLED and look for the PC GUI application project. Follow the steps in the right pane of Resource Explorer to import, compile, program, and run the embedded half of this example.
- 4. Browse to and run the *LED_BOOST_PC_GUI.exe* GUI. The program shown in Figure 5 should appear. This executable resides next to the embedded example application in Resource Explorer.

olor						Ē	Aut	omatic	: LED Control	
ue ring:	Target Current.	0.00	50 10	8	8	ð.	-	0.05	0.000 A	Blue Current:
een ring:	Target Current:	0.00	2.9.2	1	111	5. 1	<u></u>	0.05	0.000 A	Green Current:
ed ring:	Target Current:	0.00	85 40	8	8) 10	- 5 - X	1	0.05	0.000 A	Red Eurrent A
LED Slev	v Rate: 400	Set								Update Role:

Figure 5. LED BoosterPack GUI

Getting Started

www.ti.com

5. Click Setup Connection and make sure the baud rate is set to 57600 and that the Boot on Connect box is unchecked.

SCI Conne	ection Properties		
Baud Rote: COM Port:	57600 COM86 COM14 COM19 COM20 COM21 COM21 COM22 COM23 COM6 COM7 COM85 Refresh Comports Find Comport	Boot on Connect Boot File:	
12			ок

Figure 6. GUI Setup Connections Window

6. Select the serial COM port. This can be found by going to:

Control Panel \rightarrow System \rightarrow Hardware tab \rightarrow Device Manager \rightarrow Ports(COM and LPT)

Look for the COM port that is named USB Serial Port (or similar) and note the number. Select this COM port in the Setup Connection window and click OK to close the window. Hint: Try selecting the largest number or refreshing the list while connecting or disconnecting the USB cable to or from the board to see which one changes.

- 7. Click Connect in the GUI main window. The status bar at the bottom left corner of the GUI turns green and says Connected once the GUI is connected.
- 8. Use the Color Presets provided or manually adjust the current level for each LED string to vary the color generated by each LED array.
- 9. When finished, set each LED string's Target Current to 0.00A and press Disconnect to terminate the connection.

4.2 Capacitive Touch Demo

The LED BoosterPack experimenter's kit comes with an MSP430 device and headers such that a user can connect the Capacitive Touch BoosterPack and use it to control the LEDs. This interface is meant to demonstrate how an OEM lighting company might implement touch-based control of LED lighting applications.

No external hardware is required to run this demo, which makes it a great demo to show when one is away from a PC. To explore deeper, the underlying reference software can be found within controlSUITE.





Figure 7. LED BoosterPack With C2000 LaunchPad and MSP430 Capacitive Touch BoosterPack

4.2.1 Hardware Setup for Capacitive Touch Demo

Perform or verify the following steps to prepare the LED BoosterPack for use with the MSP430 Capacitive Touch BoosterPack.

- 1. Verify the following jumper and switch settings on the LED BoosterPack:
 - (a) A jumper is not placed on J2.
 - (b) A jumper is not placed on J8.
 - (c) The switch S1 is in the up position.
- 2. Verify the following jumper and switch settings on the C2000 LaunchPad:
 - (a) A jumper is placed on JP1.
 - (b) A jumper is placed on JP2.
 - (c) A jumper is placed on JP3.
 - (d) Switches in S1 are all in the up position.
 - (e) The switch S4 is in the down position.
- 3. Insert a C2000 LaunchPad into the header marked J3, J9 and J4, J10 on the LED BoosterPack.
- 4. Insert an MSP430 Capacitive Touch BoosterPack onto the headers marked J6 and J7.
- 5. Connect the LED BoosterPack to the included power adapter and plug in the adapter to the mains power.
- 6. Connect the LaunchPad to the PC using the USB cable included with the C2000 LaunchPad.



Hardware Resource Mapping

4.2.2 Software Setup for Capacitive Touch Demo

- 1. Start Code Composer Studio version 5.
- 2. In the TI Resource Explorer, look for an entry called controlSUITE and expand the Development Tools section.
- 3. Expand the entry for *BOOSTXL-C2KLED* and look for the capacitive touch demo application project. Follow the steps in the right pane of Resource Explorer to import, compile, program, and run the example.
- 4. After the example is running, the LEDs can be controlled as follows:
 - (a) Press the Center button twice to initially turn the LEDs ON.
 - (b) Spinning one's finger around the touch wheel, while the LEDs are ON, cycles through the color spectrum.
 - (c) Pressing the Center button again turns the LEDs OFF.
 - (d) Subsequent (single) presses of the Center button turns the LEDs ON or OFF.

5 Hardware Resource Mapping

5.1 Resource Allocation

Figure 8 shows the various stages of the board in a circuit diagram format and illustrates the major connections and feedback values being mapped to the C2000 MCU. Table 2 lists these resources. For more detailed information, see the schematics and the device-specific data sheets.

PWM/ADC Channel	Description
ADC-B6	Input voltage sense
PWM-1A	Boost 1 PWM signal
PWM-1B	Boost 2 PWM signal
ADC-B1	Boost 1 output voltage sense
ADC-B2	Boost 2 output voltage sense
ADC-A2	Boost 1 output current sense
ADC-A1	Boost 2 output current sense
PWM-2A	Boost 3 PWM signal
ADC-B4	Boost 3 output voltage sense
ADC-A6	Boost 3 output current sense
	PWM/ADC Channel ADC-B6 PWM-1A PWM-1B ADC-B1 ADC-B2 ADC-A2 ADC-A2 ADC-A1 PWM-2A ADC-B4 ADC-B4 ADC-A6

Table 2. PWM and ADC Resource Allocation





Figure 8. LED BoosterPack Circuit Diagram

5.2 Jumpers, Connectors, and Switches

Table 3 lists the jumpers, connectors, and switches available on the board. Figure 9 shows the location of these items with help of a board image.

J1	Barrel Jack for main power connection (6 V-48 V)
J2	Jumper to connect BoosterPack 3.3 V to LaunchPad Headers
J8	Jumper to connect BoosterPack 5 V to LaunchPad Headers
J3, J9 and J4, J10 and J11	LaunchPadXL Socket
J6 and J7	Capacitive Touch BoosterPack Headers
S1	MSP430 Serial Disconnect Switch
J5	MSP430 Programming Header

Table 3. Description of Jumpers, Connectors, and Switches



Figure 9. LED BoosterPack Jumper, Connector, and Switch Locations

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Mobile Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated